



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240215001.1

**Qualification of RFAB using qualified Process Technology and Die Revision for select devices
Change Notification / Sample Request**

Date: February 15, 2024

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240215001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV5055A1QDBZR	NULL
DRV5055A2QDBZR	NULL
DRV5055A3QDBZR	NULL
DRV5055A4QDBZR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240215001.1		PCN Date:	February 15, 2024																			
Title:	Qualification of RFAB using qualified Process Technology and Die Revision for select devices																						
Customer Contact:	Change Management team		Dept:	Quality Services																			
Proposed 1st Ship Date:	May 15, 2024		Sample requests accepted until:	March 16, 2024*																			
*Sample requests received after March 16, 2024 will not be supported.																							
Change Type:																							
☐	Assembly Site	☒	Design	☐	Wafer Bump Material																		
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process																		
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site																		
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material																		
☐	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process																		
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology in addition to a new die revision option for the devices listed below in the product affected section.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Technology</th> <th colspan="3">New Technology</th> </tr> <tr> <th>Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MIHO</td> <td>LBC8</td> <td>200 mm</td> <td>RFAB</td> <td>LBC9</td> <td>300 mm</td> </tr> </tbody> </table>						Current Technology			New Technology			Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter	MIHO	LBC8	200 mm	RFAB	LBC9	300 mm
Current Technology			New Technology																				
Fab Site	Process	Wafer Diameter	Fab Site	Process	Wafer Diameter																		
MIHO	LBC8	200 mm	RFAB	LBC9	300 mm																		
The die was also changed as a result of the process change.																							
Qual details are provided in the Qual Data Section.																							
Reason for Change:																							
Continuity of supply																							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																							
None																							
Changes to product identification resulting from this PCN:																							
Fab Site Information:																							
Chip Site		Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City																			
MIHO8		MH8	JPN	Ibaraki																			
RFAB		RFB	USA	Richardson																			
Die Rev:																							
Current		New																					
Die Rev [2P]		Die Rev [2P]																					
B		C																					
Sample product shipping label (not actual product label)																							



MADE IN: Malaysia
2DC: 2Q:

MSL 2 / 260C/1 YEAR SEAL DT
MSL 1 / 235C/UNLIM 03/29/04

OPT:
ITEM:
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

DRV5055A1QDBZR DRV5055A2QDBZR DRV5055A3QDBZR DRV5055A4QDBZR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	Qual Device: DRV5055A2QDBZR	Qual Device: DRV5055A3QDBZR	Qual Device: DRV5055A4QDBZR	QBS Reference: TLV62569DBVR	QBS Reference: TLV62569DBVR	QBS Reference: DRV5013AQDBZRQ1	QBS Reference: DRV5013AQDBZRQ1	QBS Reference: TL431BQDBZRQ1	QBS Reference: PTMAG5253BA3QDBZR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/150C	1500 Cycles	-	-	-	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-	3/135/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	2000 Hours	-	-	-	-	-	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	1000 Hours	-	-	-	-	-	-	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0	-	-	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/3000/0	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	Qual Device: DRV5055A2QDBZR	Qual Device: DRV5055A3QDBZR	Qual Device: DRV5055A4QDBZR	QBS Reference: TLV62569DBVR	QBS Reference: TLV62569DBVR	QBS Reference: DRV5013AQDBZRQ1	QBS Reference: DRV5013AQDBZRQ1	QBS Reference: TL431BQDBZRQ1	QBS Reference: PTMAG5253BA3QDBZR
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder	-	-	-	-	-	-	-	-	-	-	1/22/0
PD	C4	Physical Dimensions	CpIo1.67	-	-	-	-	-	-	-	3/30/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	3500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
LU	E4	Leach-Up	Per JE5078	-	-	-	1/3/0	-	1/6/0	3/9/0	1/6/0	1/6/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Distributions	CpIo1.67 Room, hot and cold	-	-	-	-	-	-	-	2/60/0	3/90/0	3/90/0	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	-	1/1/0	-	-	-	-	1/1/0	-

- QBS: Qual By Similarity
- Qual Device DRV5055A1QDBZR is qualified at MSL1 260C
- Qual Device DRV5055A2QDBZR is qualified at MSL1 260C
- Qual Device DRV5055A3QDBZR is qualified at MSL1 260C
- Qual Device DRV5055A4QDBZR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JE5047 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2303-072

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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